Renesas Electronics America Inc - R5F211A2NP#U0 Datasheet

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I^{2}C, SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-WFQFN Exposed Pad
Supplier Device Package	28-HWQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f211a2np-u0

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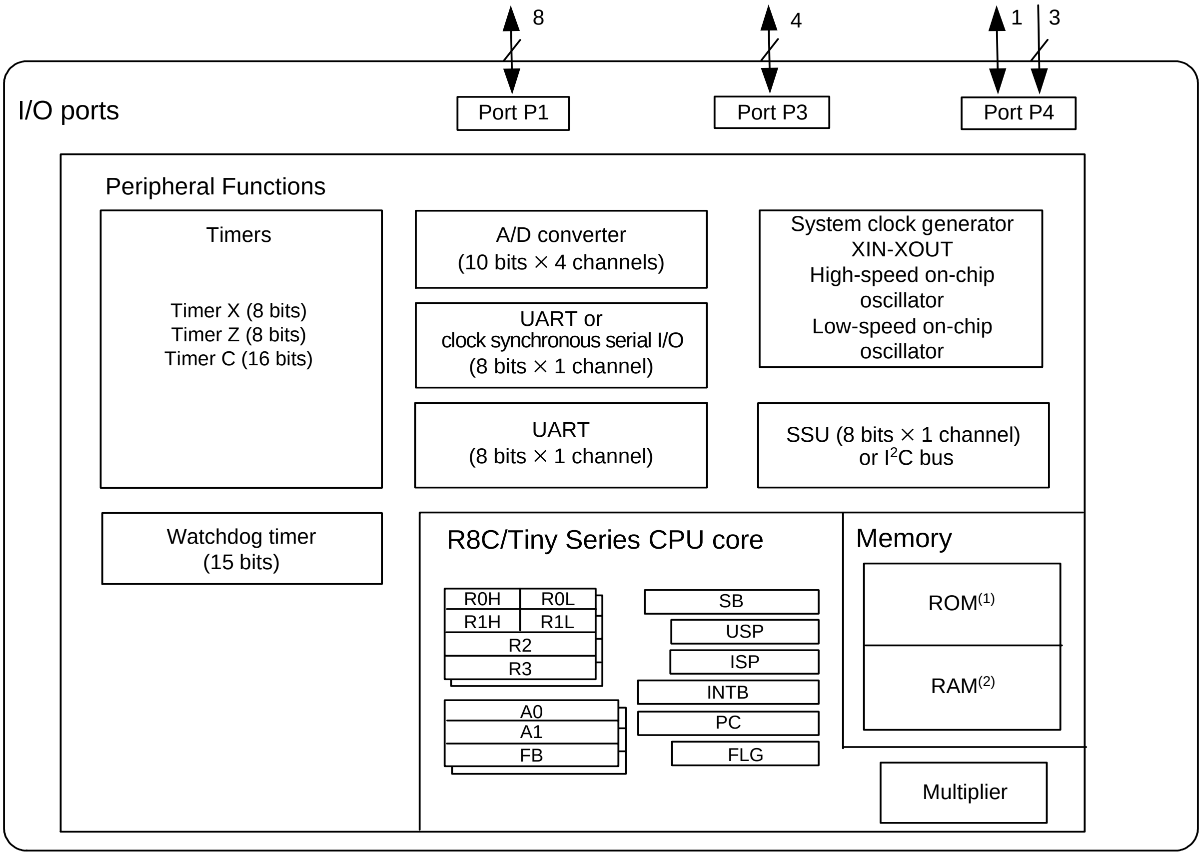
1.3 Block Diagram

Figure 1.1 shows a Block Diagram.



NOTES:
1. ROM size varies with MCU type.
2. RAM size varies with MCU type.

Figure 1.1 Block Diagram

1.4 Product Information

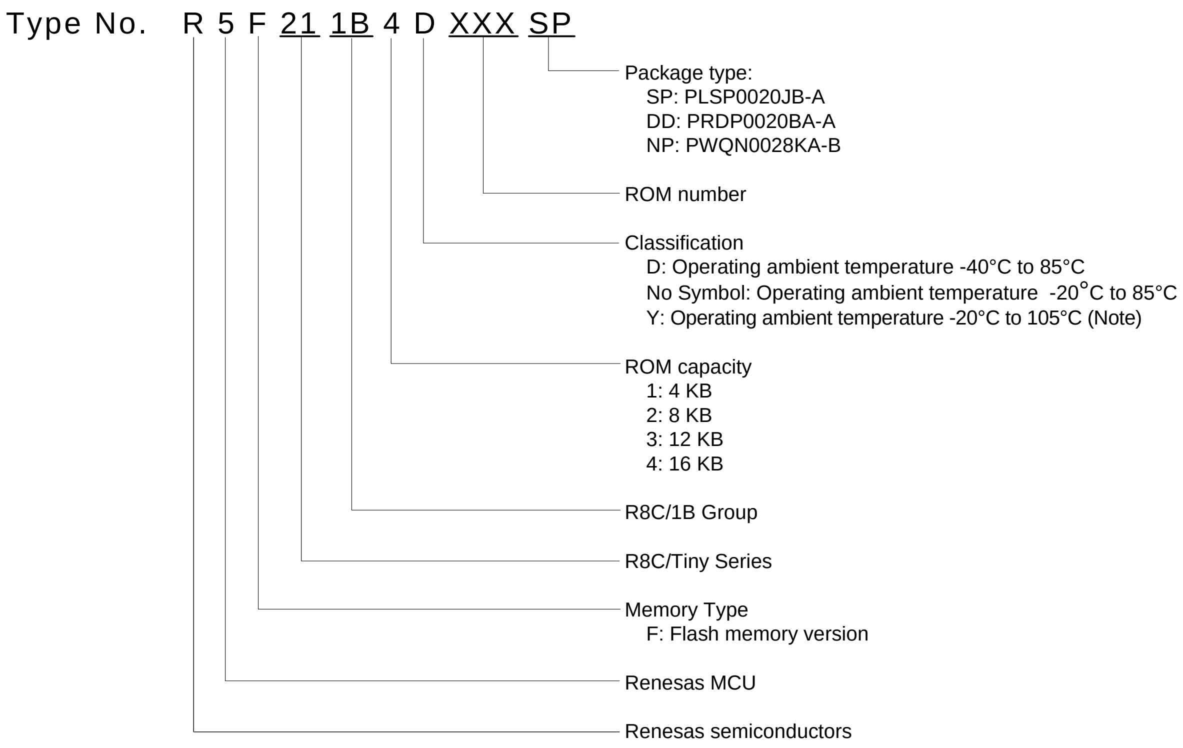
Table 1.3 lists Product Information for R8C/1A Group and Table 1.4 lists Product Information for R8C/1B Group.

Table 1.3 Product Information for R8C/1A Group **Current of October 2006**

Type No.	ROM Capacity	RAM Capacity	Package Type	Remarks
R5F211A1SP	4 Kbytes	384 bytes	PLSP0020JB-A	
R5F211A2SP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3SP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4SP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1DSP	4 Kbytes	384 bytes	PLSP0020JB-A	D version
R5F211A2DSP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3DSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4DSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1DD	4 Kbytes	384 bytes	PRDP0020BA-A	
R5F211A2DD	8 Kbytes	512 bytes	PRDP0020BA-A	
R5F211A3DD	12 Kbytes	768 bytes	PRDP0020BA-A	
R5F211A4DD	16 Kbytes	1 Kbyte	PRDP0020BA-A	
R5F211A2NP	8 Kbytes	512 bytes	PWQN0028KA-B	
R5F211A3NP	12 Kbytes	768 bytes	PWQN0028KA-B	
R5F211A4NP	16 Kbytes	1 Kbyte	PWQN0028KA-B	
R5F211A1XXXSP	4 Kbytes	384 bytes	PLSP0020JB-A	Factory programming product (1)
R5F211A2XXXSP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3XXXSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4XXXSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1DXXXSP	4 Kbytes	384 bytes	PLSP0020JB-A	D version
R5F211A2DXXXSP	8 Kbytes	512 bytes	PLSP0020JB-A	
R5F211A3DXXXSP	12 Kbytes	768 bytes	PLSP0020JB-A	
R5F211A4DXXXSP	16 Kbytes	1 Kbyte	PLSP0020JB-A	
R5F211A1XXXDD	4 Kbytes	384 bytes	PRDP0020BA-A	Factory programming product (1)
R5F211A2XXXDD	8 Kbytes	512 bytes	PRDP0020BA-A	
R5F211A3XXXDD	12 Kbytes	768 bytes	PRDP0020BA-A	
R5F211A4XXXDD	16 Kbytes	1 Kbyte	PRDP0020BA-A	
R5F211A2XXXNP	8 Kbytes	512 bytes	PWQN0028KA-B	
R5F211A3XXXNP	12 Kbytes	768 bytes	PWQN0028KA-B	
R5F211A4XXXNP	16 Kbytes	1 Kbyte	PWQN0028KA-B	

NOTE:

1. The user ROM is programmed before shipment.



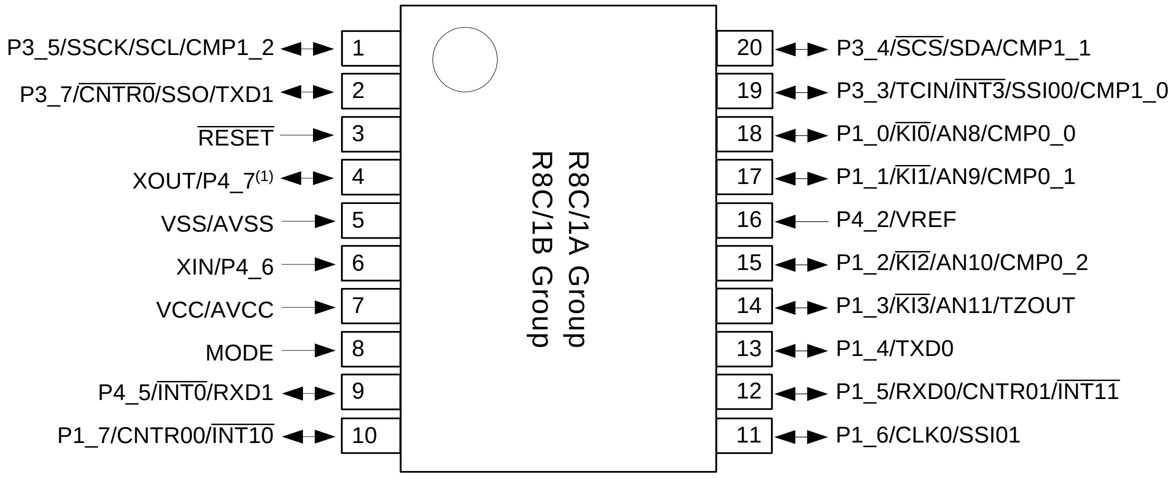
NOTE: Please contact Renesas Technology sales offices for the Y version.

Figure 1.3 Type Number, Memory Size, and Package of R8C/1B Group

1.5 Pin Assignments

Figure 1.4 shows Pin Assignments for PLSP0020JB-A Package (Top View), Figure 1.5 shows Pin Assignments for PRDP0020BA-A Package (Top View) and Figure 1.6 shows Pin Assignments for PWQN0028KA-B Package (Top View).

PIN assignments (top view)

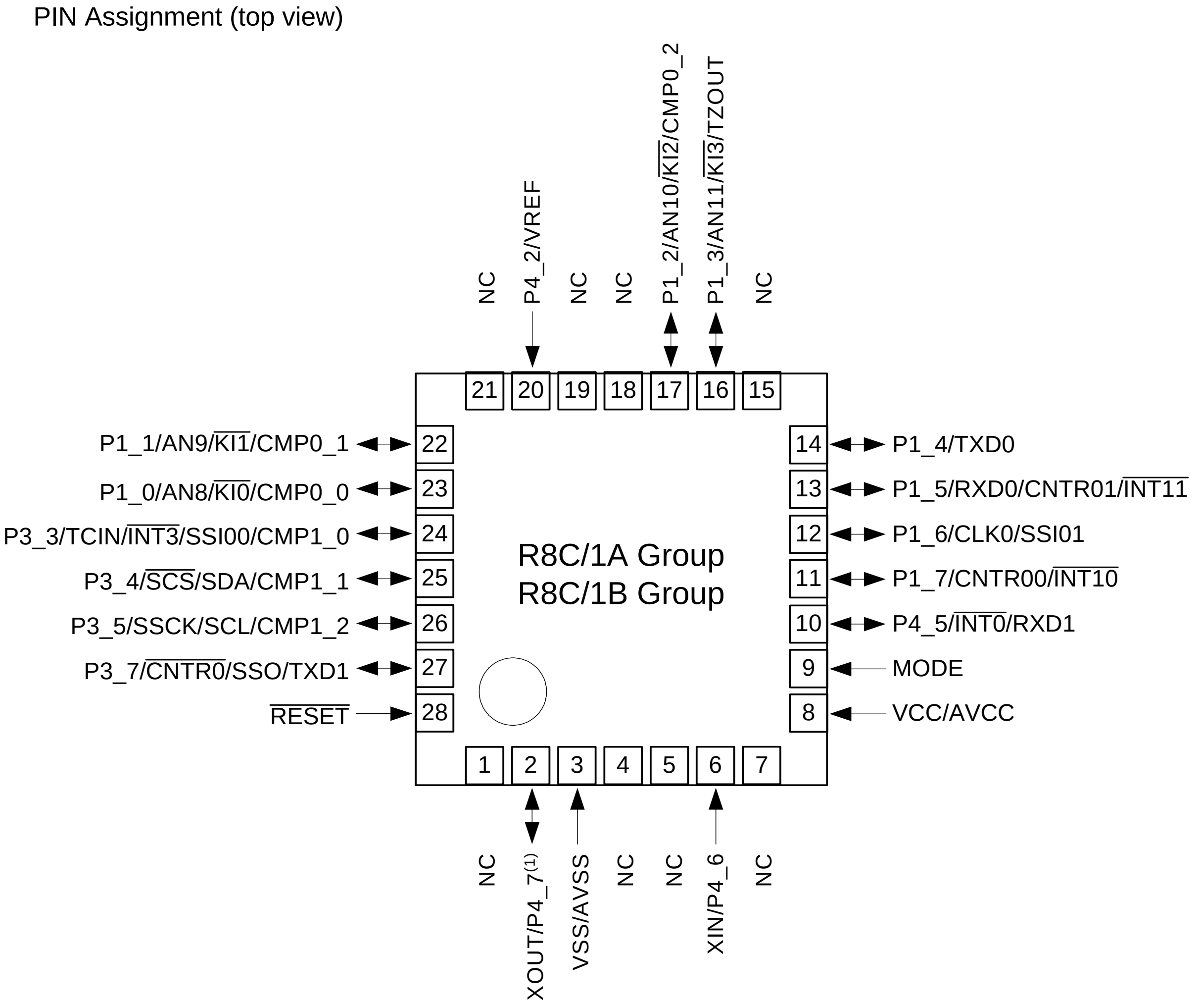


NOTE:

1. P4_7 is an input-only port.

Package: PLSP0020JB-A (20P2F-A)

Figure 1.4 Pin Assignments for PLSP0020JB-A Package (Top View)



NOTES:
1. P4_7 is a port for the input.

Package: PWQN0028KA-B(28PJW-B)

Figure 1.6 **Pin Assignments for PWQN0028KA-B Package (Top View)**

1.6 Pin Functions

Table 1.5 lists Pin Functions, Table 1.6 lists Pin Name Information by Pin Number of PLSP0020JB-A, PRDP0020BA-A Packages and Table 1.7 lists Pin Name Information by Pin Number of PWQN0028KA-B Package.

Table 1.5 Pin Functions

Type	Symbol	I/O Type	Description
Power Supply Input	VCC, VSS	I	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog Power Supply Input	AVCC, AVSS	I	Power supply for the A/D converter Connect a capacitor between AVCC and AVSS.
Reset Input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
Main Clock Input	XIN	I	These pins are provided for main clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an external clock, input it to the XIN pin and leave the XOUT pin open.
Main Clock Output	XOUT	O	
$\overline{\text{INT}}$ Interrupt	$\overline{\text{INT0}}$, $\overline{\text{INT1}}$, $\overline{\text{INT3}}$	I	INT interrupt input pins
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer X	CNTR0	I/O	Timer X I/O pin
	$\overline{\text{CNTR0}}$	O	Timer X output pin
Timer Z	TZOUT	O	Timer Z output pin
Timer C	TCIN	I	Timer C input pin
	CMP0_0 to CMP0_2, CMP1_0 to CMP1_2	O	Timer C output pins
Serial Interface	CLK0	I/O	Transfer clock I/O pin
	RXD0, RXD1	I	Serial data input pins
	TXD0, TXD1	O	Serial data output pins
Clock synchronous serial I/O with chip select (SSU)	SSI00, SSI01	I/O	Data I/O pin.
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin
I^{2}C bus Interface	SCL	I/O	Clock I/O pin
	SDA	I/O	Data I/O pin
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter
A/D Converter	AN8 to AN11	I	Analog input pins to A/D converter
I/O Port	P1_0 to P1_7, P3_3 to P3_5, P3_7, P4_5	I/O	CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in the port to be directed for input or output individually. Any port set to input can be set to use a pull-up resistor or not by a program. P1_0 to P1_3 also function as LED drive ports.
Input Port	P4_2, P4_6, P4_7	I	Input-only ports

I: Input O: Output I/O: Input and output

Table 1.6 Pin Name Information by Pin Number of PLSP0020JB-A, PRDP0020BA-A Packages

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	Clock Synchronous Serial I/O with Chip Select	I^2C bus Interface	A/D Converter
1		P3_5		CMP1_2		SSCK	SCL	
2		P3_7		$\overline{\text{CNTR0}}$	TXD1	SSO		
3	$\overline{\text{RESET}}$							
4	XOUT	P4_7						
5	VSS/AVSS							
6	XIN	P4_6						
7	VCC/AVCC							
8	MODE							
9		P4_5	$\overline{\text{INT0}}$		RXD1			
10		P1_7	$\overline{\text{INT10}}$	CNTR00				
11		P1_6			CLK0	SSI01		
12		P1_5	$\overline{\text{INT11}}$	CNTR01	RXD0			
13		P1_4			TXD0			
14		P1_3	$\overline{\text{KI3}}$	TZOUT				AN11
15		P1_2	$\overline{\text{KI2}}$	CMP0_2				AN10
16	VREF	P4_2						
17		P1_1	$\overline{\text{KI1}}$	CMP0_1				AN9
18		P1_0	$\overline{\text{KI0}}$	CMP0_0				AN8
19		P3_3	$\overline{\text{INT3}}$	TCIN/ CMP1_0		SSI00		
20		P3_4		CMP1_1		$\overline{\text{SCS}}$	SDA	

Table 1.7 Pin Name Information by Pin Number of PWQN0028KA-B Package

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	Clock Synchronous Serial I/O with Chip Select	I^2C bus Interface	A/D Converter
1	NC							
2	XOUT	P4_7						
3	VSS/AVSS							
4	NC							
5	NC							
6	XIN	P4_6						
7	NC							
8	VCC/AVCC							
9	MODE							
10		P4_5	$\overline{\text{INT0}}$		RXD1			
11		P1_7	$\overline{\text{INT10}}$	CNTR00				
12		P1_6			CLK0	SSI01		
13		P1_5	$\overline{\text{INT11}}$	CNTR01	RXD0			
14		P1_4			TXD0			
15	NC							
16		P1_3	$\overline{\text{KI3}}$	TZOUT				AN11
17		P1_2	$\overline{\text{KI2}}$	CMP0_2				AN10
18	NC							
19	NC							
20	VREF	P4_2						
21	NC							
22		P1_1	$\overline{\text{KI1}}$	CMP0_1				AN9
23		P1_0	$\overline{\text{KI0}}$	CMP0_0				AN8
24		P3_3	$\overline{\text{INT3}}$	TCIN/CMP1_0		SSI00		
25		P3_4		CMP1_1		$\overline{\text{SCS}}$	SDA	
26		P3_5		CMP1_2		SSCK	SCL	
27		P3_7		$\overline{\text{CNTR0}}$	TXD1	SSO		
28	$\overline{\text{RESET}}$							

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

Table 4.4 SFR Information (4)(1)

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00000XXXb
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h			
00E1h	Port P1 Register	P1	XXh
00E2h			
00E3h	Port P1 Direction Register	PD1	00h
00E4h			
00E5h	Port P3 Register	P3	XXh
00E6h			
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h			
00FAh			
00FBh			
00FCh	Pull-Up Control Register 0	PUR0	00XX0000b
00FDh	Pull-Up Control Register 1	PUR1	XXXXXX0Xb
00FEh	Port P1 Drive Capacity Control Register	DRR	00h
00FFh	Timer C Output Control Register	TCOUT	00h
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
0FFFFh	Optional Function Select Register	OFS	(2)

X: Undefined

NOTES:

1. Blank regions, 0100h to 01B2h and 01B8h to 02FFh are all reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a user program. Use a flash programmer to write to it.

5. Electrical Characteristics

Please contact Renesas Technology sales offices for the electrical characteristics in the Y version (Topr = -20°C to 105°C).

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}	Supply voltage	V_{CC} = AV_{CC}	-0.3 to 6.5	V
AV_{CC}	Analog supply voltage	V_{CC} = AV_{CC}	-0.3 to 6.5	V
V_I	Input voltage		-0.3 to V_{CC}+0.3	V
V_O	Output voltage		-0.3 to V_{CC}+0.3	V
P_d	Power dissipation	T_{opr} = 25°C	300	mW
T_{opr}	Operating ambient temperature		-20 to 85 / -40 to 85 (D version)	°C
T_{stg}	Storage temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V_{CC}	Supply voltage			2.7	–	5.5	V
AV_{CC}	Analog supply voltage			–	V_{CC}	–	V
V_{SS}	Supply voltage			–	0	–	V
AV_{SS}	Analog supply voltage			–	0	–	V
V_{IH}	Input “H” voltage			0.8V_{CC}	–	V_{CC}	V
V_{IL}	Input “L” voltage			0	–	0.2V_{CC}	V
$I_{OH(sum)}$	Peak sum output “H” current	Sum of all pins I_{OH} (peak)		–	–	-60	mA
$I_{OH(peak)}$	Peak output “H” current			–	–	-10	mA
$I_{OH(avg)}$	Average output “H” current			–	–	-5	mA
$I_{OL(sum)}$	Peak sum output “L” currents	Sum of all pins I_{OL} (peak)		–	–	60	mA
$I_{OL(peak)}$	Peak output “L” currents	Except P1_0 to P1_3		–	–	10	mA
		P1_0 to P1_3	Drive capacity HIGH	–	–	30	mA
			Drive capacity LOW	–	–	10	mA
$I_{OL(avg)}$	Average output “L” current	Except P1_0 to P1_3		–	–	5	mA
		P1_0 to P1_3	Drive capacity HIGH	–	–	15	mA
			Drive capacity LOW	–	–	5	mA
$f_{(XIN)}$	Main clock input oscillation frequency		3.0 V ≤ V_{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V_{CC} < 3.0 V	0	–	10	MHz
–	System clock	OCD2 = 0 Main clock selected	3.0 V ≤ V_{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V_{CC} < 3.0 V	0	–	10	MHz
		OCD2 = 1 On-chip oscillator clock selected	HRA01 = 0 Low-speed on-chip oscillator clock selected	–	125	–	kHz
			HRA01 = 1 High-speed on-chip oscillator clock selected	–	8	–	MHz

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. Typical values when average output current is 100 ms.

Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance[2]		10,000[3]	–	–	times
–	Byte program time (Program/erase endurance ≤ 1,000 times)		–	50	400	µs
–	Byte program time (Program/erase endurance > 1,000 times)		–	65	–	µs
–	Block erase time (Program/erase endurance ≤ 1,000 times)		–	0.2	9	s
–	Block erase time (Program/erase endurance > 1,000 times)		–	0.3	–	s
$t_{d(SR-SUS)}$	Time Delay from suspend request until suspend		–	–	97+CPU clock × 6 cycles	µs
–	Interval from erase start/restart until following suspend request		650	–	–	µs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3+CPU clock × 4 cycles	µs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		-20[8]	–	85	°C
–	Data hold time[9]	Ambient temperature = 55 °C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = –20 to 85 °C / –40 to 85 °C, unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. If emergency processing is required, a suspend request can be generated independent of this characteristic. In that case the normal time delay to suspend can be applied to the request. However, we recommend that a suspend request with an interval of less than 650 µs is only used once because, if the suspend state continues, erasure cannot operate and the incidence of erasure error rises.
5. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
6. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
7. Customers desiring programming/erasure failure rate information should contact their Renesas technical support representative.
8. -40 °C for D version.
9. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.10 High-Speed On-Chip Oscillator Circuit Electrical Characteristics

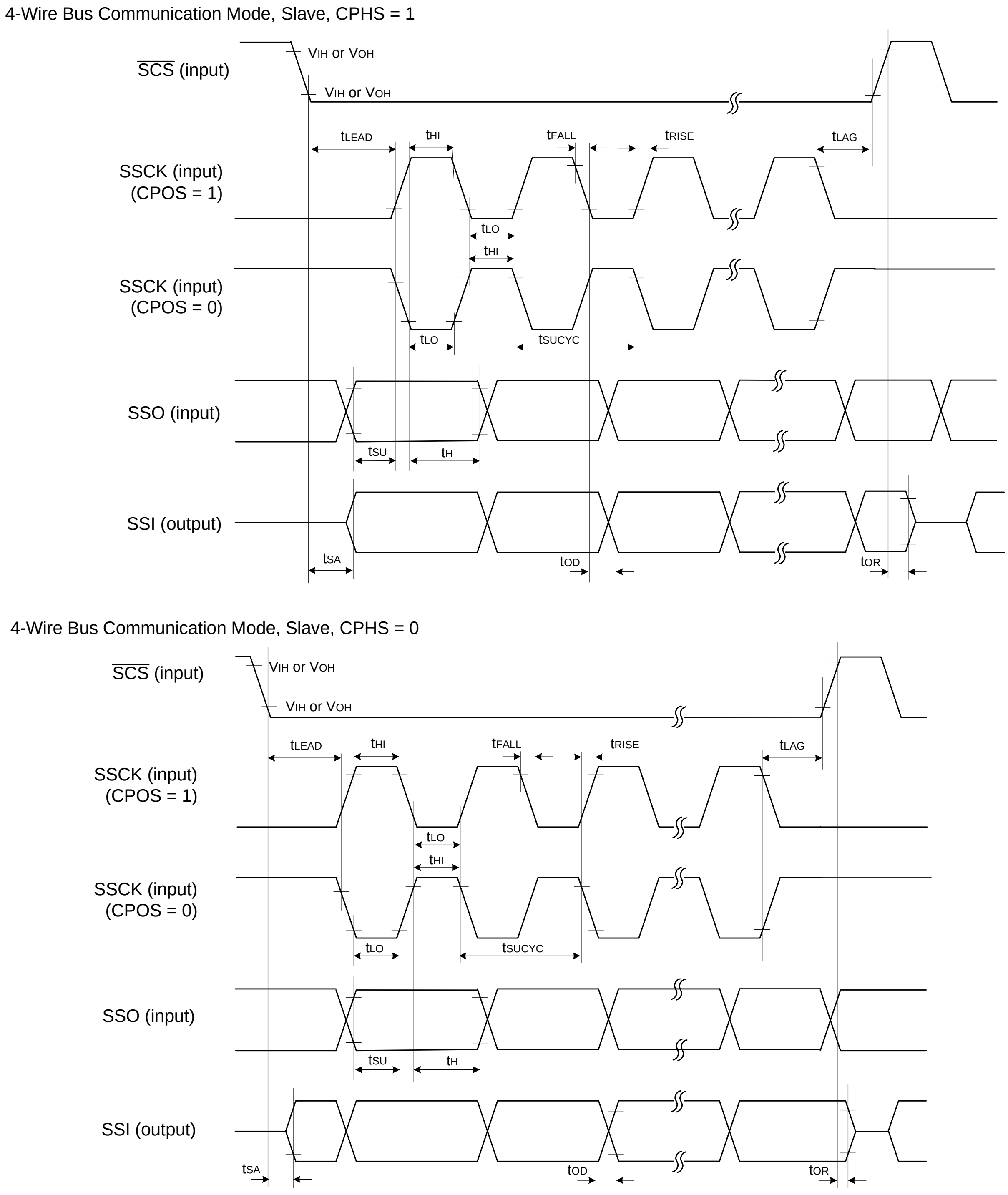
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
–	High-speed on-chip oscillator frequency when the reset is deasserted	V_{CC} = 5.0 V, T_{opr} = 25 °C	–	8	–	MHz
–	High-speed on-chip oscillator frequency temperature • supply voltage dependence(2)	0 to +60 °C/5 V ± 5 %(3)	7.76	–	8.24	MHz
		-20 to +85 °C/2.7 to 5.5 V(3)	7.68	–	8.32	MHz
		-40 to +85 °C/2.7 to 5.5 V(3)	7.44	–	8.32	MHz

NOTES:
1. The measurement condition is V_{CC} = 5.0 V and T_{opr} = 25 °C.
2. Refer to **10.6.4 High-Speed On-Chip Oscillator Clock** for notes on high-speed on-chip oscillator clock.
3. The standard value shows when the HRA1 register is assumed as the value in shipping and the HRA2 register value is set to 00h.

Table 5.11 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on(2)		1	–	2000	µs
$t_{d(R-S)}$	STOP exit time(3)		–	–	150	µs

NOTES:
1. The measurement condition is V_{CC} = 2.7 to 5.5 V and T_{opr} = 25 °C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until CPU clock supply starts after the interrupt is acknowledged to exit stop mode.



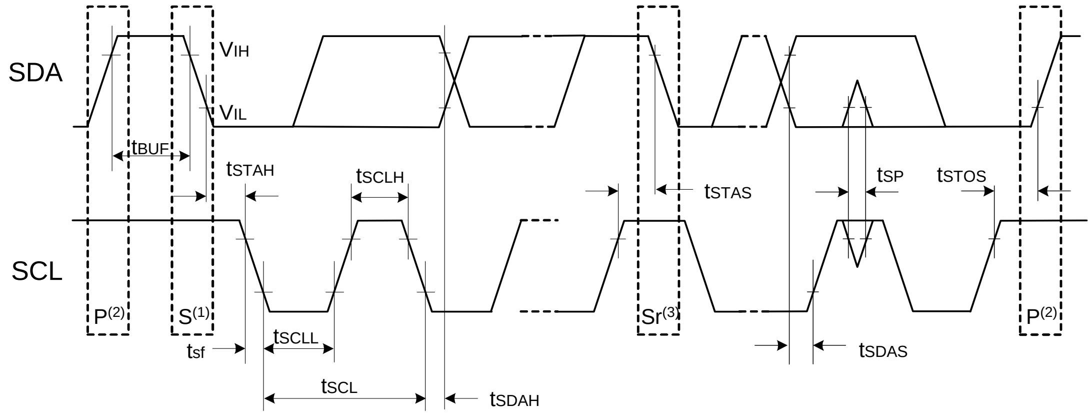
CPHS, CPOS: Bits in SSMR register

Figure 5.5 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Slave)

Table 5.13 Timing Requirements of I^{2}C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{SCL}	SCL input cycle time		$12t_{CYC}+600$(2)	–	–	ns
t_{SCLH}	SCL input “H” width		$3t_{CYC}+300$(2)	–	–	ns
t_{SCLL}	SCL input “L” width		$5t_{CYC}+300$(2)	–	–	ns
t_{sf}	SCL, SDA input fall time		–	–	300	ns
t_{SP}	SCL, SDA input spike pulse rejection time		–	–	$1t_{CYC}$(2)	ns
t_{BUF}	SDA input bus-free time		$5t_{CYC}$(2)	–	–	ns
t_{STAH}	Start condition input hold time		$3t_{CYC}$(2)	–	–	ns
t_{STAS}	Retransmit start condition input setup time		$3t_{CYC}$(2)	–	–	ns
t_{STOS}	Stop condition input setup time		$3t_{CYC}$(2)	–	–	ns
t_{SDAS}	Data input setup time		$1t_{CYC}+20$(2)	–	–	ns
t_{SDAH}	Data input hold time		0	–	–	ns

NOTES:
1. V_{CC} = 2.7 to 5.5 V, V_{SS} = 0 V and Ta = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. $1t_{CYC} = 1/f1(s)$



NOTES:
1. Start condition
2. Stop condition
3. Retransmit start condition

Figure 5.7 I/O Timing of I^{2}C bus Interface

Table 5.21 Electrical Characteristics (3) [V_{CC} = 3V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Except X_{OUT}	I_{OH} = -1 mA		V_{CC} – 0.5	–	V_{CC}	V
		X_{OUT}	Drive capacity HIGH	I_{OH} = -0.1 mA	V_{CC} – 0.5	–	V_{CC}	V
			Drive capacity LOW	I_{OH} = -50 μA	V_{CC} – 0.5	–	V_{CC}	V
V_{OL}	Output “L” voltage	Except P1_0 to P1_3, X_{OUT}	I_{OL} = 1 mA		–	–	0.5	V
		P1_0 to P1_3	Drive capacity HIGH	I_{OL} = 2 mA	–	–	0.5	V
			Drive capacity LOW	I_{OL} = 1 mA	–	–	0.5	V
		X_{OUT}	Drive capacity HIGH	I_{OL} = 0.1 mA	–	–	0.5	V
			Drive capacity LOW	I_{OL} = 50 μA	–	–	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, CNTR0, CNTR1, TCIN, RXD0			0.2	–	0.8	V
		$\overline{RESET}$			0.2	–	1.8	V
I_{IH}	Input “H” current		VI = 3 V		–	–	4.0	μA
I_{IL}	Input “L” current		VI = 0 V		–	–	-4.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V		66	160	500	kΩ
R_{fXIN}	Feedback resistance	XIN			–	3.0	–	MΩ
f_{RING-S}	Low-speed on-chip oscillator frequency				40	125	250	kHz
V_{RAM}	RAM hold voltage		During stop mode		2.0	–	–	V

NOTE:

1. V_{CC} = 2.7 to 3.3 V at T_{opr} = -20 to 85 °C / -40 to 85 °C, f(XIN) = 10 MHz, unless otherwise specified.

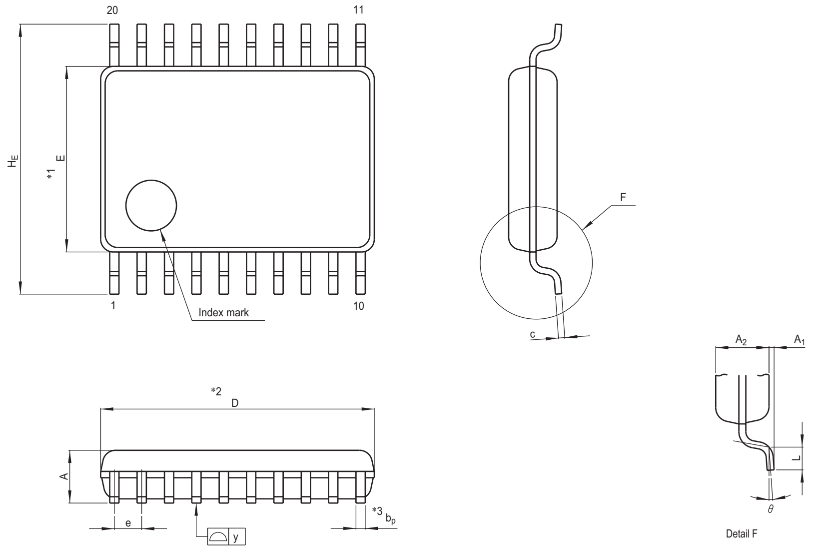
Table 5.22 Electrical Characteristics (4) [Vcc = 3 V] (Topr = -40 to 85 °C, unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
ICC	Power supply current (VCC = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are VSS, A/D converter is stopped	High-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	8	13	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	7	12	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5	–	mA
		Medium-speed mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.6	–	mA
		High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	3.5	7.5	mA
			Main clock off High-speed on-chip oscillator on = 8 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	100	280	µA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = 0	–	37	74	µA
		Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = 0	–	35	70	µA
		Stop mode	Main clock off, Topr = 25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = 0	–	0.7	3.0	µA

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.

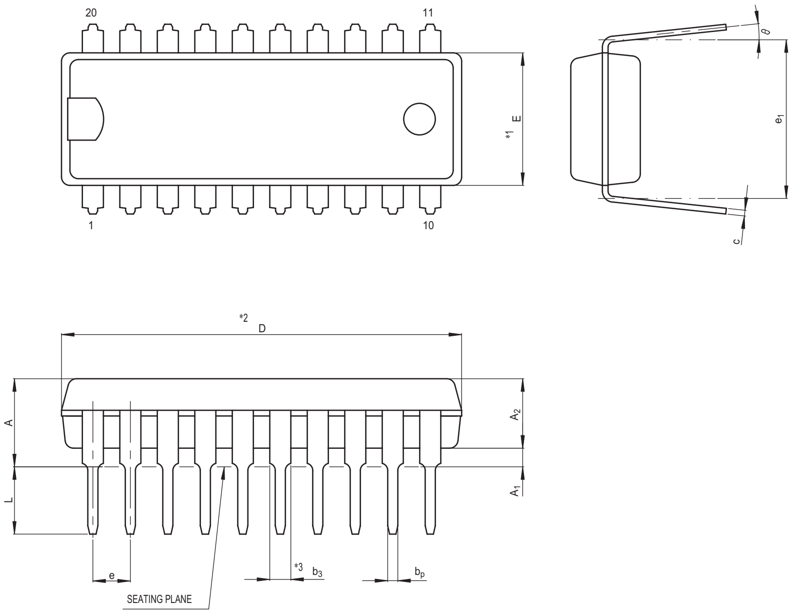
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LSSOP20-4.4x6.5-0.65	PLSP0020JB-A	20P2F-A	0.1g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.4	6.5	6.6
E	4.3	4.4	4.5
A_2	—	1.15	—
A	—	—	1.45
A_1	0	0.1	0.2
b_p	0.17	0.22	0.32
c	0.13	0.15	0.2
θ	0°	—	10°
H_E	6.2	6.4	6.6
e	0.53	0.65	0.77
y	—	—	0.10
L	0.3	0.5	0.7

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SDIP20-6.3x19-1.78	PRDP0020BA-A	20P4B	1.0g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	7.32	7.62	7.92
D	18.8	19.0	19.2
E	6.15	6.3	6.45
A	—	—	4.5
A_1	0.51	—	—
A_2	—	3.3	—
b_p	0.38	0.48	0.58
b_3	0.9	1.0	1.3
c	0.22	0.27	0.34
θ	0°	—	15°
e	1.528	1.778	2.028
L	3.0	—	—

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